# DB3S314J

### Silicon epitaxial planar type

For high speed switching circuits DB3J314J in SSMini3 type package

#### Features

- Short reverse recovery time  $t_{rr}$
- Small reverse current I<sub>R</sub>
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)
- Marking Symbol: 4Y

#### Basic Part Number

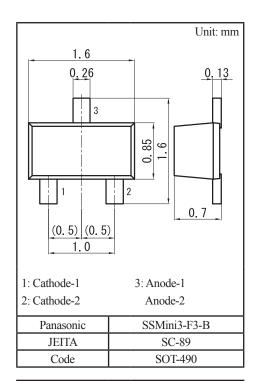
Dual DB2J314 (Common Anode)

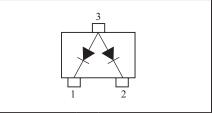
#### Packaging

DB3S314J0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

| 0 4                           |           |                   |                             |    |  |  |  |  |  |
|-------------------------------|-----------|-------------------|-----------------------------|----|--|--|--|--|--|
| Parameter                     | Symbol    | Rating            | Unit                        |    |  |  |  |  |  |
| Reverse voltage               |           | V <sub>R</sub>    | 30                          | V  |  |  |  |  |  |
| Maximum peak reverse voltage  |           | V <sub>RM</sub>   | 30                          | V  |  |  |  |  |  |
| Forward current               | Single    | т                 | 30                          | mA |  |  |  |  |  |
|                               | Double *1 | - I <sub>F</sub>  | 20                          |    |  |  |  |  |  |
| Peak forward current          | Single    | т                 | 150                         | mA |  |  |  |  |  |
|                               | Double *1 | - I <sub>FM</sub> | 110                         |    |  |  |  |  |  |
| Junction temperature          |           | Tj                | 125                         | °C |  |  |  |  |  |
| Operating ambient temperature |           | T <sub>opr</sub>  | T <sub>opr</sub> -40 to +85 |    |  |  |  |  |  |
| Storage temperature           |           | T <sub>stg</sub>  | -55 to +125                 | °C |  |  |  |  |  |
|                               |           |                   |                             |    |  |  |  |  |  |





Note) \*1: Value of each diode in double diodes used.

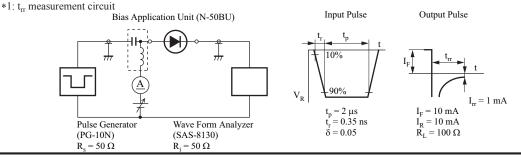
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

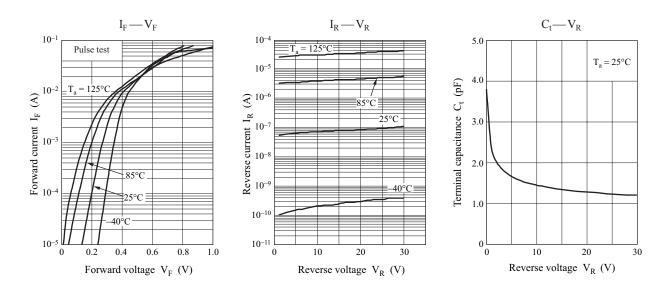
| Parameter                | Symbol          | Conditions   | Min | Тур | Max | Unit |
|--------------------------|-----------------|--|-----|-----|-----|------|
| Forward voltage          | V <sub>F1</sub> | $I_F = 1 \text{ mA}$   |     |     | 0.4 | v    |
|                          | V <sub>F2</sub> | $I_F = 30 \text{ mA}$  |     |     | 1.0 |      |
| Reverse current          | I <sub>R</sub>  | $V_R = 30 V$   |     |     | 300 | nA   |
| Terminal capacitance     | Ct              | $V_{R} = 10 V, f = 1 MHz$  |     | 1.5 |     | pF   |
| Reverse recovery time *1 | t <sub>rr</sub> | $I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$ |     | 1.0 |     | ns   |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

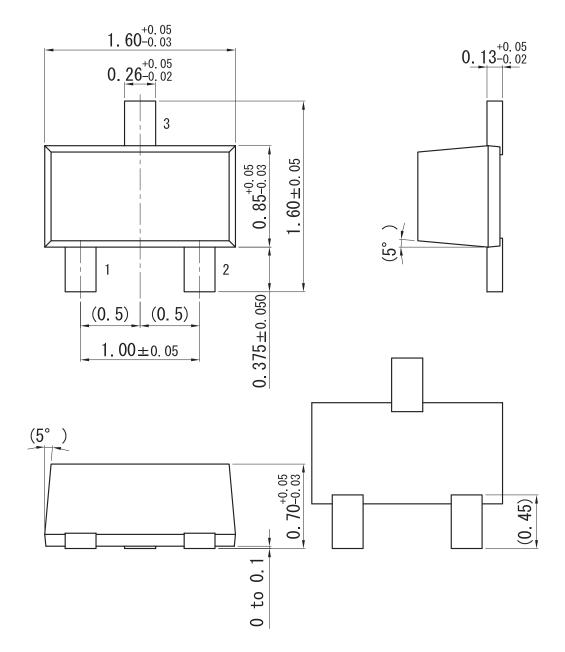
3. Absolute frequency of input and output is 2 GHz



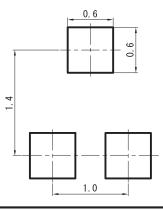


### SSMini3-F3-B

Unit: mm



Land Pattern (Reference) (Unit: mm)



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